

**ABSTRACT OF THE DISCLOSURE**

The present invention relates to a method of packaging optical parts for optical communication. According to the method of the present invention, there are advantages  
5 in that a packaging process for optical parts is automated to improve productivity and to obtain price competitiveness and uniformity of quality, and a high frequency heater for locally transferring heat to only a solder preform is used to minimize thermal deformation of areas except a soldering area, thereby achieving highly reliable packaging of the optical parts.